

Announcement

Executive Meeting

January 2015

Important Information

All statements other than statements of historical facts included in this Presentation are or may be forward-looking statements. Forward-looking statements include but are not limited to those using words such as “expect”, “anticipate”, “believe”, “estimate”, “intend”, “project”, “plan”, “strategy”, “forecast” and similar expressions or future or conditional verbs such as “if”, “will”, “would”, “should”, “could”, “may” and “might”. These statements reflect the parties’ current expectations, beliefs, hopes, intentions or strategies regarding the future and assumptions in light of currently available information. Such forward-looking statements are not guarantees of future performance or events and involve known and unknown risks and uncertainties. Accordingly, actual results may differ materially from those described in such forward-looking statements. You should not place undue reliance on such forward-looking statements, and neither Jiangsu Changjiang Electronics Technology Co., Ltd. (“JCET”) nor STATS ChipPAC Ltd. (“STATS”) undertakes any obligation to update publicly or revise any forward-looking statements, subject to compliance with all applicable laws and regulations and/or the rules of the SGX-ST and/or any other regulatory or supervisory body or agency.

The financial data for JCET included in this Presentation are derived from JCET’s consolidated financial statements prepared in accordance with Chinese Accounting Standards (“PRC GAAP”), while the financial data for STATS included in this Presentation are derived from STATS’ consolidated financial statements prepared in accordance with Singapore Financial Reporting Standards (“SFRS”). PRC GAAP may differ from SFRS in material respects. Further, JCET’s fiscal year ends on December 31 while STATS’ 52-53 week fiscal year ends on the Sunday nearest and prior to December 31. STATS financial statements are presented in U.S. dollars, while JCET’s consolidated financial statements are presented in RMB and the amounts included in this Presentation are based on translations into U.S. dollars based on the exchange rate of RMB6.21 per US$1.00 for convenience.

This Presentation also includes the presentation of EBITDA and Adjusted EBITDA. JCET defines EBITDA as Revenue less cost of service less operating / value-added tax less sales expense less G&A expenses plus depreciation and amortization of intangibles and LT expenses, while STATS defines Adjusted EBITDA as net income attributable to STATS ChipPAC Ltd. plus income tax expense, interest expense, net, depreciation and amortisation, restructuring charges, share-based compensation, goodwill and equipment impairment, tender offer, debt exchange or debt redemption expenses and write-off of debt issuance costs. These are financial measures that are not based on any generally accepted accounting principles (“GAAP”). These non-GAAP measures are not a measurement of financial performance or liquidity under any GAAP. In addition, EBITDA is not a standardized term and different companies (including JCET and STATS) define EBITDA differently; hence, a direct comparison between companies using such term may not be possible.

Agenda

1. Introductions: Transaction Overview, Message from Chairman Wang
2. Overview of Combined Company
3. Rationale and Impact of the Acquisition? Opportunity Discussion
4. What does this mean for you?

Compelling Deal Rationale



1. Elevation to #3 OSAT Player Globally by Total Revenue (2013)[1]
2. Highly Complementary Geographic Coverage
3. Comprehensive Portfolio of OSAT Services
4. Advanced IP / Technology Portfolio
5. Significant Scope for Revenue and Cost Synergies

(1) Source: Gartner.

1. Transaction Overview

Overview of Transaction

Overview	■ **Acquisition of 100% of STATS ChipPAC Ltd. ("SCL") for US$780mm** ■ **Transaction to exclude the Taiwan Subsidiaries of SCL** ■ The Taiwan Subsidiaries of STATS ChipPAC will be restructured to give current STATS ChipPAC shareholders the opportunity to maintain their effective ownership of the Taiwan Subsidiaries and in a manner consistent with the objective of enabling smooth continuation of the business and operational relationships of the Taiwan Companies
Company Name	■ **STATS ChipPAC (business unit within JCET)**
Operations	■ **Headquarters in Jiangsu, China**
Management	■ **Group Chairman: Wang Xin Chao** ■ **Current SCL CEO and President: Tan Lay Koon**
Transaction Timing	■ **Expected to close in calendar 2Q – 3Q 2015**
Conditions Include	■ **Shareholder & Regulatory Approvals** ■ **Antitrust Approvals**

Jiangsu Changjiang Electronics Technology Overview

Company Highlights

No. 1	• Packaging and testing company in China by total revenue (2013) [1]
No. 6	• Packaging and testing company in the world by total revenue (2013) [1]
US$1,764 Million	• Market Capitalization as of 31 Oct, 2014 [2]
US$850 Million[4]	• Revenue in 2013
~12,000	• Employees
Overview	• Founded in 1998 and listed on Shanghai Stock Exchange (600584-CN) in 2003
Facilities	• Four manufacturing facilities in Jiangsu and Anhui provinces
Product & Capabilities	• Capabilities in leaded, discrete, laminate, bumping and WLCSP

Chairman Bio

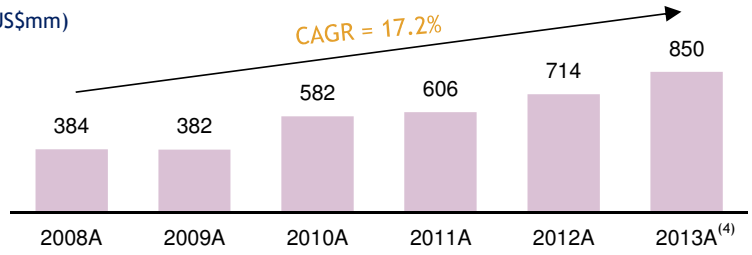


Wang Xin Chao
Chairman of JCET

- Chairman of IC Packaging and Testing Industry Chain Technology Innovation Strategic Alliance
- Chairman of Jiangsu Semiconductor Industry Association
- Significant operations experience and years of experience in the OSAT industry
- Senior economist

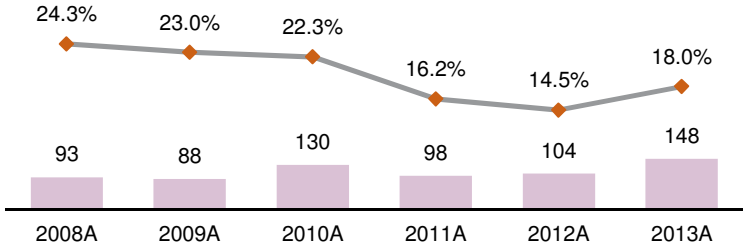
Revenue

(US$mm)



EBITDA & EBITDA Margin [3]

(US$mm)



Source: Company filings, Gartner and FactSet. RMB:USD=0.1610.
(1) Source: Gartner. (2) Based on the last trading price as of Oct 31, 2014, the date prior to share suspension. (3) EBITDA calculated as Revenue - cost of service - operating / value-added tax - sales expense – G&A expenses + depreciation + amortization of intangibles and LT expenses. (4) JCET's 2013 revenues from Gartner research.

2. Overview of Combined Company

Company Snapshots

	长电科技 CHANGJIANG ELEC.TECH.	STATSChipPAC
Founded	• 1998	• 1994
Headquarters	• Jiangsu, PRC	• Singapore
Employees	• ~12,000	• 10,793
Manufacturing Facilities	• 4 manufacturing facilities in Jiangsu and Anhui provinces	• 3 manufacturing facilities in Singapore, South Korea and China
Market Cap.	• US$1,764 million (1)	• US$780 million (excluding Taiwan) (2)
3Q14 Net Debt (3)	• US$116 million	• US$984 million
LTM–3Q14 Revenue	• US$963 million	• US$1,574 million
2013 Revenue by Product Line	• Advanced Packaging: 35.0% (4) • Wirebond Packaging: 59.5% (5) • Chip sales: 5.4%	• Advanced Packaging: 46.9% • Wirebond Packaging: 30.8% • Test: 22.3%

Source: Company filings and FactSet. RMB:USD=0.1610.
(1) Based on the last trading price as of Oct 31, 2014, the date prior to share suspension. (2) Based on offer consideration for SCL excluding Taiwan subsidiaries. (3) Defined as total debt less cash and cash equivalents. (4) Advanced packaging consists of wafer scale ICs, substrate ICs and Camera modules. (5) Wirebond packaging consists of leadframe ICs and discrete devices.

JCET + SCL Facilities Overview

1



Singapore (SCS)
- Yishun Plant (808,000sqf)

Singapore (SCH-WD)
- Woodlands R&D Center (51,129 sqf)

2



China (SCC)
- Shanghai Plant (983,276 sqf)
- Largest full turnkey assembly and test service provider in China

3



Korea (SCK3)
- Incheon / DuckPyong Plant (1M+ sqf)
- New facility specialized in advanced array flip chip / SD / CSP and BGA.
- Second facility focused on probe/final test and pkg.

4



Campus 1: JCET HQ, (including C1 plant)
- No. 275, Middle Binjiang Road, Jiangyin (660,570 sqf)

5



Campus 3: C3, C5, C6 and MIS Factories
- No.78, Changshan Road, Jiangyin (2,010,332 sqf)

6

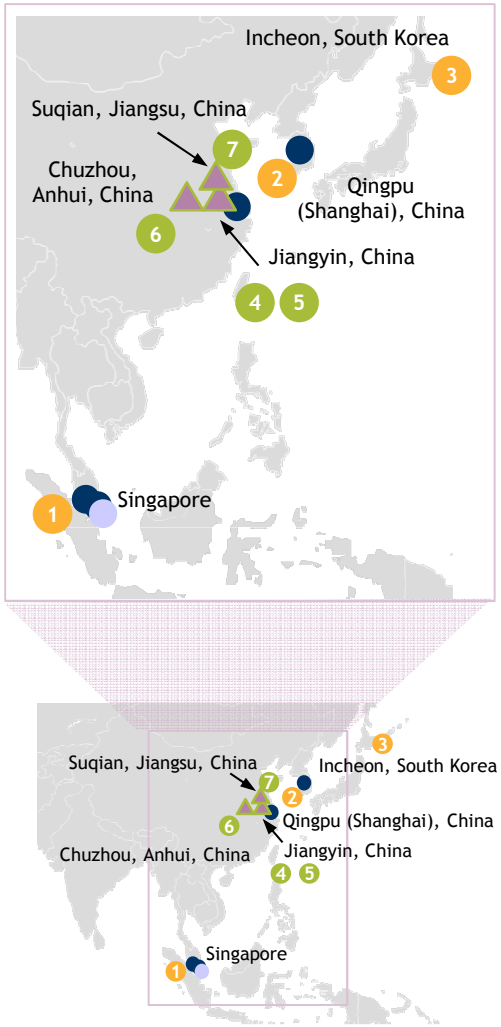


Small-Signal Package Factory(Chuzhou, Anhui)
- No. 999 Century Road Chengbei Industrial Park of Economic Development Zone Chuzhou, Anhui (1,844,217 sqf)

7



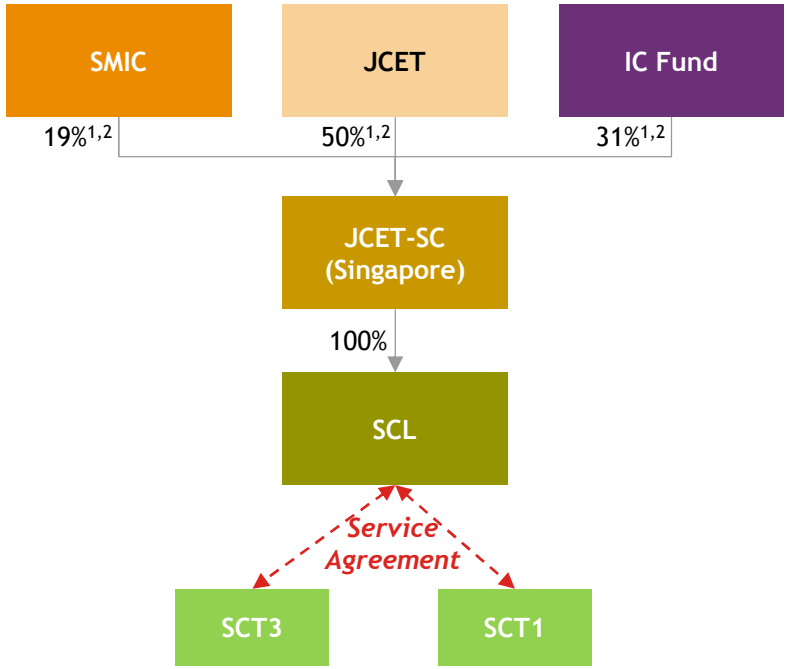
Power Package Factory (Suqian, Jiangsu)
- No. 5, Putuoshan Avenue, Suzhou-Suqian Industrial Park, Suqian, Jiangsu Province (904,168 sqf)



Source: Company website and latest filings.

Company Structure

Summary Company Structure



Board of Directors of JCET-SC (Singapore)

- Wang Xinchao - JCET
- Chew Hwee Seng Jimmy - JCET
- Woo Kwek Kiong - JCET
- Steve Xin Liang - JCET
- Cui Dong - SMIC
- Fan Xiao Ning – IC Fund
- Ren Kai – IC Fund

Commentary

1. SCL will be organized as an autonomous Business Unit under the Chairman

2. Intention is for key SCL management team to remain intact and unchanged and for local sales team to remain in place

3. Factories will operate under their own P&L (vs. the previous centralized operation) — Synergies gained through corporate / HQ structure

4. Taiwan subsidiaries will be carved out, and a service agreement between SCL and the Taiwan subsidiaries for 5 years is proposed to be implemented

1. Represents indirect ownership in JCET-SC (Singapore). **2.** JCET, IC Fund and SMIC have 51%, 29% and 20% shareholding in Suzhou Changjiang Electric Xinke Investment Co., Ltd. ("HoldCo"), which in turn has 98% shareholding in Suzhou Changjiang Electric Xinpeng Investment Co., Ltd. ("SCXI"). IC Fund owns the remaining 2% shareholding in SCXI. JCET-SC is 100% owned by SCXI.

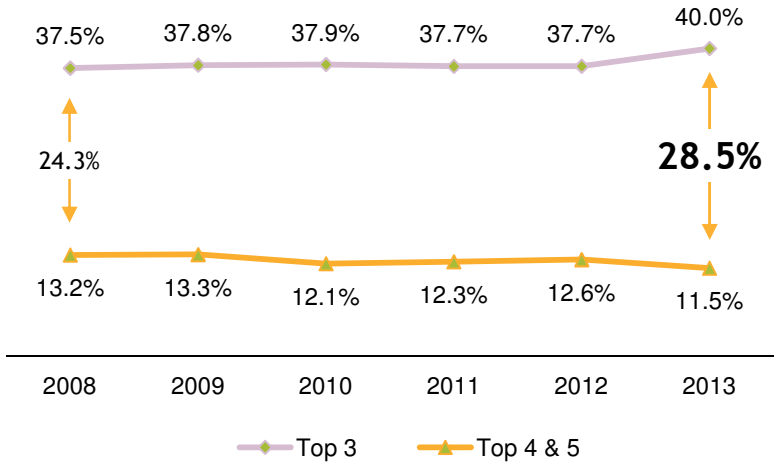
Description of JCET Consortium Partners

Company	Business Description
JCET **HQ:** Jiangyin, China **Market Cap:** US$1,764mm	• Founded in 1998 and listed on Shanghai Stock Exchange (600584-CN) in 2003, JCET engages in packaging, testing and sale of semiconductor chips • JCET operates as a leading packaging service provider in China • Key products include lead frame packaging, laminate packaging and packaging materials • Products mainly sold to Mainland China, Hong Kong, Taiwan, Europe, and the U.S.
SMIC **HQ:** Shanghai, China **Market Cap:** US$3,329mm	• Headquartered in Shanghai, China, Semiconductor Manufacturing International Corporation ("SMIC"; NYSE: SMI; SEHK: 981) is one of the leading semiconductor foundries in the world and the largest and most advanced foundry in mainland China • SMIC provides integrated circuit (IC) foundry and technology services at 0.35-micron to 28-nanometer • SMIC has facilities in Shanghai, Beijing and Tianjin, and is also developing new facilities in Beijing and Shenzhen
IC Fund **Fund Size:** US$20.6bn (RMB120bn)	• Incorporated on 24 September 2014, the IC Fund invests primarily in IC chip manufacturing as well as chip designing, packaging, test and equipment & materials • Investors in the IC Fund include CDB Capital Co., Ltd., China National Tobacco Corporation, Beijing Yizhuang International Investment and Development Co., Ltd., China Mobile Communications Corporation, Shanghai Guosheng (Group) Co., Ltd., China Electronics Technology Group Corporation, Beijing Purple Communications Technology Group Ltd. and Sino IC Capital.

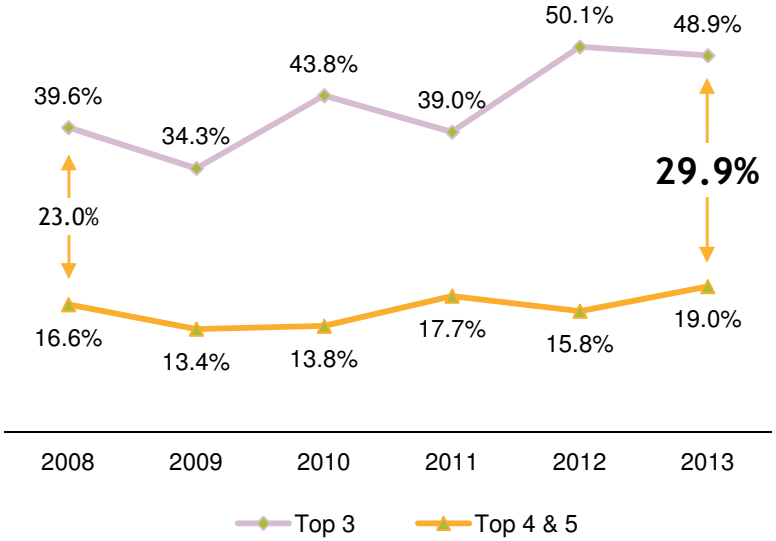
3. Transaction Rationale

OSAT Industry is Transforming – Scale Matters!

Increasing Gap Between Top 3 & others…
(Estimated OSAT Market Share by total revenue, %)



… With Further Concentration of Capex Spend
(Capex Spend as % of Total OSAT Capex)



- Intensified competition, higher capital intensity & greater ASP erosion have resulted in consolidation among OSATs and an increasing gap between the top 3 and other players
- What is required to be successful:
  - Scale, technology & ability to invest to meet rising complexity of IC design, functional integration & form-factor miniaturization

Source: Gartner.
Note: Top 3 OSAT players defined as ASE, Amkor and SPIL. Top 4 & 5 OSAT players defined as STATS and Powertech.

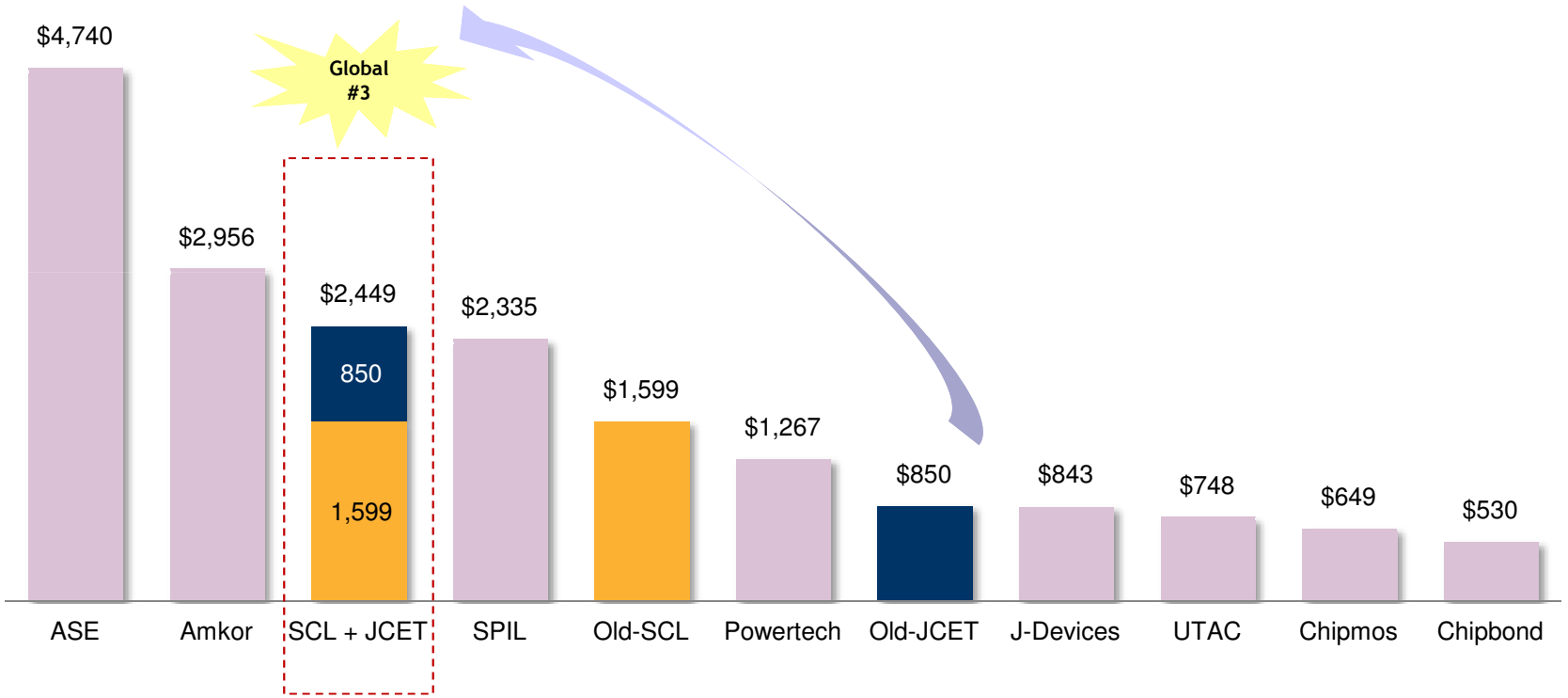
Rationale for the Acquisition

1 Elevation to #3 OSAT Player Globally by Total Revenue	• Creates #1 OSAT player in China and #3 OSAT player globally[1] • Combined company with revenues of $2.4 bn in 2013 and estimated nearly 10% global market share by total revenue (2013)[1]
2 Highly Complementary Geographic Coverage	• Global manufacturing, R&D and sales footprint with significant presence in China • Strategic and consolidated footprint in proximity to wafer fabrication hubs in Asia • Greater revenue diversity across geographies with optimal blend of China and global clients
3 Comprehensive Portfolio of OSAT Services	• Comprehensive portfolio of packaging solutions ranging from discrete, low-lead to the most advanced flip-chip and wafer level offerings • Well positioned to service customers that seek a one-stop service provider
4 Advanced IP / Technology Portfolio	• Significant position in advanced technology with industry leading positions in fcCSP and eWLB fan-out technology • Supported by strong IP portfolio and innovation around advanced technologies
5 Significant Scope for Revenue and Cost Synergies	• SG&A cost synergies from elimination of overlapping functions, savings on business expansion costs, improved R&D efficacy and facilities integration • Revenue synergies potential from cross-selling of products, geographical diversity and utilization improvement

(1) Based on 2013 revenues. Source: Gartner and company filings.

Elevation to #3 OSAT Player Globally

Top 10 OSAT Players by 2013 Total Revenue
(US$ mm)



Source: Gartner.

Complementary Geographic Fit

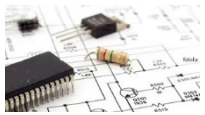
Mobile Convergence



Consumer Electronics



Diversified IDM



Power Management



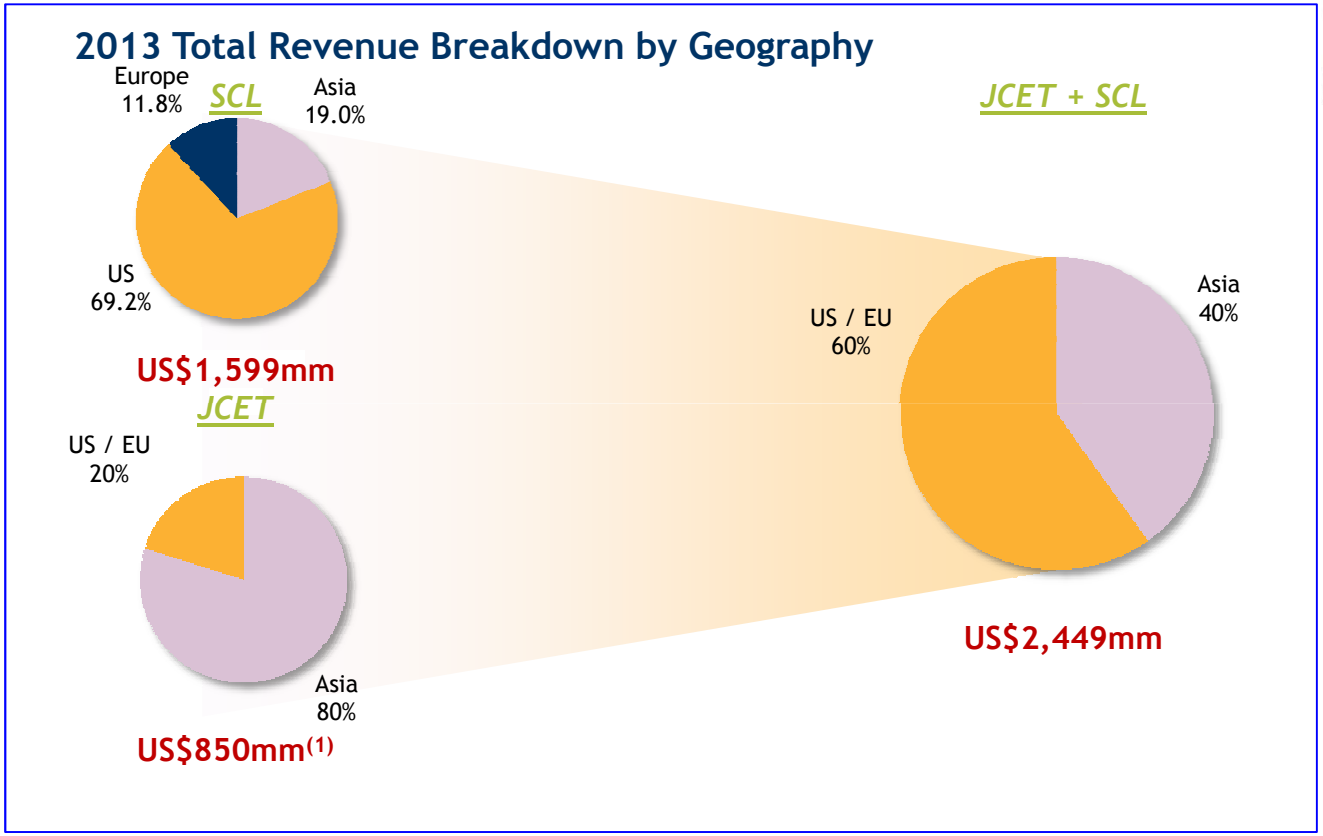
Analog & Mixed Signal



Storage / Memory



2013 Total Revenue Breakdown by Geography



(1) JCET's 2013 revenues from Gartner research.

Combined Product and Service Offerings

Wirebond Packaging

Discrete

Packaging Type

- TO
- SOD
- SOT
- FBP
- DFN

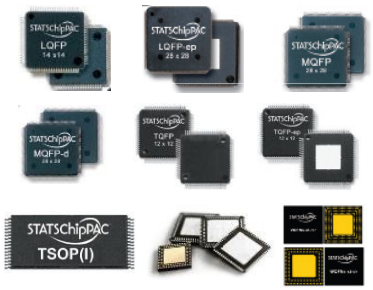
Product Category

- Diode
- Transistor
- Darlington transistor
- Digital transistor
- MOSFET
- Regulator circuit
- Energy-saving lamp charger switch
- SCR

Leaded

Packaging Type

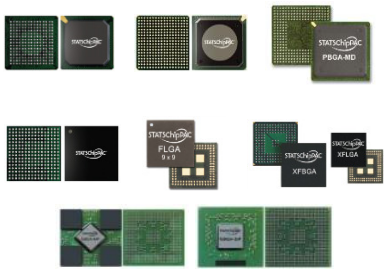
- TSOP
- QFP
- QFN
- SOD
- SOT
- FBP
- SIP
- SOP
- DIP
- FCOL



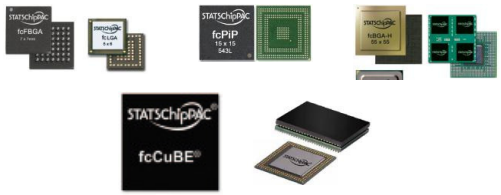
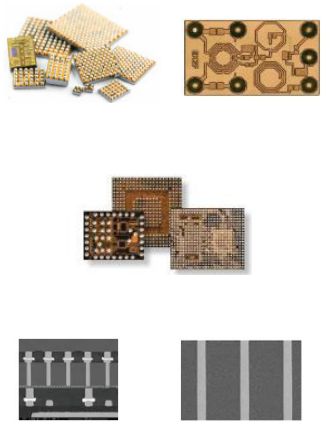
Laminate

Packaging Type

- PBGA
- FBGA (Stacked Die)
- SIP
- FCBGA
- LGA
- MEMS
- Smart Card



Combined Product and Service Offerings (Cont'd)

Advanced Packaging	**Flip Chip**	**Packaging Type** • fcFBGA • fcBGA • fcPiP • fcCuBE • bare die fcPoP			
	Wafer Level	**Fan-in** • WLCSP • IPD **Fan-out** • eWLB **Through Silicon Via** • TSV			
Testing	**Test Platform**	**Mixed Signal** • UltraFLEX, FLEX, Tiger • Catalyst • 93K PS400, PS800 • ETS 300 / 364 • Fusion CX	**Digital** • UltraFLEX, FLEX / microFLEX, Catalyst • 93K PS400, PS800 • ETS 300 / 364 • Fusion CX	**RF** • UltraFLEX, FLEX Catalyst • 93K Portscale • ETS 200 / 364 • Fusion CX	**Memory** • Magnum, • Maverick (1PT / 1 VT / 1 / 2GT) • T5503, T5581H • T5585

Combined Company Financial Overview

US$ mm	长电科技 CHANGJIANG ELEC.TECH.	STATSChipPAC	Combined
LTM-3Q14 Revenue	$963	$1,574	$2,537
LTM-3Q14 EBITDA	$171 (1)	$348 (2)	$519
LTM-3Q14 EBITDA Margin (%)	17.8% (1)	22.1% (2)	20.5%
3Q14 Net Debt	$116	$984	$1,100
3Q14 Net Debt / LTM EBITDA	0.7x (1)	2.8x (2)	2.1x

Synergy Opportunities

Opex Synergies

- Improvement of supply chain and procurement efficiencies on greater economies of scale
- Integration of regional sales and service operations
- Elimination of overlapping functions

Capex / Financing

- Centralized CAPEX spending and to facilitate improved ROIC
- Improved R&D efficacy via sharing of technology and IP
- Savings on business expansion costs

Revenue Synergies

- Cross-selling of products to broad customer base
- Revenue growth from expansion into new geographies
- Utilization improvement across existing plants

Source: Company filings. RMB:USD=0.1610.
(1) EBITDA calculated as Revenue - cost of service - operating / value-added tax - sales expense – G&A expenses + depreciation + amortization of intangibles and LT expenses.
(2) Adjusted EBITDA as net income attributable to STATS ChipPAC Ltd. plus income tax expense, interest expense, net, depreciation and amortisation, restructuring charges, share-based compensation, goodwill and equipment impairment, tender offer, debt exchange or debt redemption expenses and write-off of debt issuance costs.

4. What Does This Mean For You?

What Does This Mean For You?

Growth	Partnership	Opportunities	Products	China Focus
	Pro-active partner looking to grow OSAT business	Ability to invest in mutually beneficial business opportunities	Full platform of packaging, assembly and test capabilities from low-end to high-end solutions	Ideal partner in JCET which is a #1 OSAT company in China
Reliability	Technology	Point of Contact	Management	Quality
	Leadership in WLP/Flip Chip now coupled with low-end 12-inch wafer technologies through JCET	Sales relationships and key contacts intended to continue as before	Key management to continue to operate the company	Absolute assurance of continued delivery of high quality services

Data Security

1. All Non SCL Business Unit employee will NOT have access to any SCL information
2. Customers' technical Information within SCL are further controlled by Site/ Role Base/Need to Know: No data exchange between SCL's Site
3. Any individual who requires access will need to apply for it and is subjected to management approval

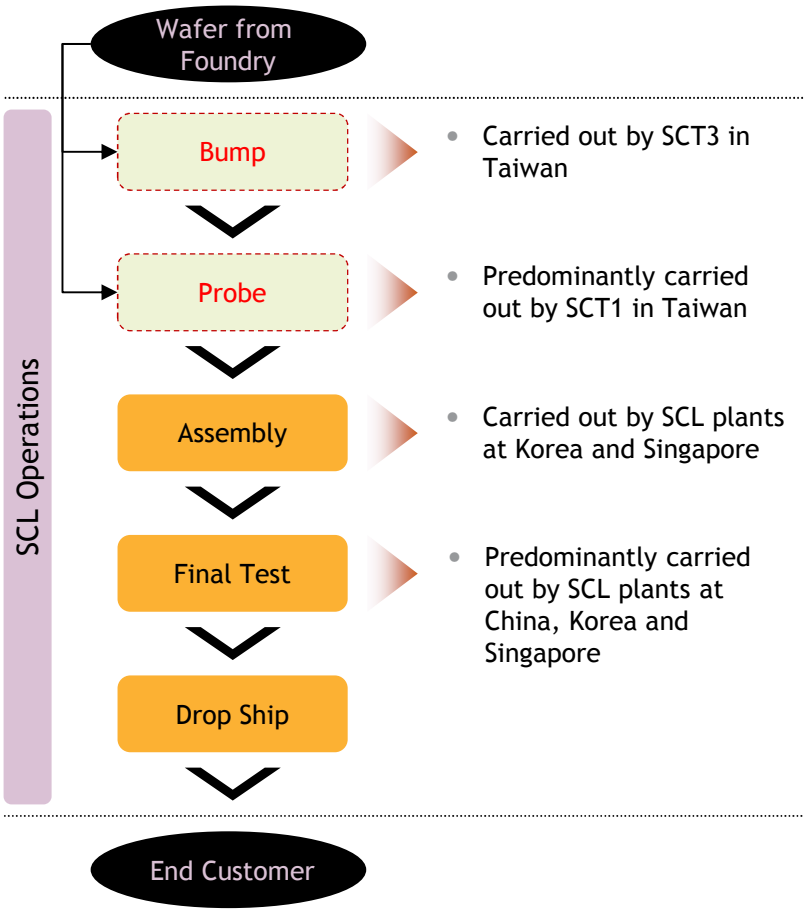
Restricted Access (Need to Know Only)

SQS	SAP	Workflow	Database	MES+
• Price • Billable Index Time • Estimate Vol. • HVM Timing	• Forecast • Price • BOM	• Bonding Diagram • Package Outline Drawing • Substrate/LF Drawing • Customer Spec • Customer Test Program Info	• Test program • STDF • Optimal Test • TUT	• Marking • Recipe • BOM • WIP Tracking

Taiwan Subsidiaries Carve-out

A Service Agreement is proposed to be implemented between SCL and the Taiwan subsidiaries to provide service continuity and full turnkey solutions to our end customers.

SCL OSAT Value Chain



Overview of Service Agreement

Rationale	• Under Taiwan law, PRC investors are restricted by the Taiwan government from acquiring "controlling" stakes in Taiwan semiconductor packaging and testing companies • Carve-out of the Taiwan subsidiaries to give current SCL shareholders the opportunity to maintain their effective ownership of the Taiwan subsidiaries • Enable a smooth continuation of the Taiwan subsidiaries as an independent entity with limited / no disruption to existing operational relationships
Overview	• SCL proposes to enter into a services agreement with the Taiwan subsidiaries to ensure that all current services provided by the two plants continue unaffected by the transaction
Tenor	• Expected to be 5 years and can be extended by the mutual agreement of the parties
Capacity	• SCT1 and SCT3 expected to commit capacity for use by SCL

Relocation of China Manufacturing Facility

SCL is relocating its manufacturing facility in Shanghai due to zoning changes, and SCL is working with the relevant PRC local authorities to identify a new location.

Overview of Plant Relocation	• Due to recent changes in the long term zoning, development and construction plans for the West Hongqiao area of China, SCL is relocating STATS ChipPAC Shanghai ("SCC") to a new manufacturing site in China • SCL will be working with the Qingpu Land Planning Bureau, the Qingpu District Land Reserve Center and the Shanghai Qingpu District Xujing Town House and Land Expropriation Compensation Office to identify a new location for the manufacturing site
Selection of New Manufacturing Site	• Focus on selecting a new location that will be in close proximity to current site • Top priority to minimize any potential disruptions to customers and employees
Timing	• Relocation of SCC to a new site is expected to take place in late 2017
Overview of SCC	• Established in 1994, SCC provides high volume, low cost turnkey solutions encompassing wafer bump, wafer probe, packaging, final test and distribution services • 983,000 square foot packaging and test operation located at No. 188 Huaxugong Road, Xujing Town, Shanghai • Offers a broad portfolio of leaded, laminate, stacked die, memory card and flip chip packages to support multiple customers in the communications, consumer and computing markets

Q&A / Next Steps

THANK YOU!



Directors' Responsibility Statements

Offeror and JCET Directors' Responsibility Statement

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